

I2C	Function	I2C Spec.	Budget Timing	I2C Slave Address (7-bit mode)
I2C-0	Rear Camera - 13M	400 Kbps	Yes.	Rear camera (IMX135) I2C address: 0X10 (Write:0x20, Read:0x21) AF driver (DW9714A) I2C address: 0x0C (Write:0x18 , Read:0x19)
	Front Camera	400 Kbps	Yes.	Front camera (GC2355) I2C address: 0x3C (Write:0x78, Read:0x79)
I2C-1	CTP	400 Kbps	Yes.	GT1151 / CTP I2C address: 0X5D (Write:0xBA, Read:0xBB) or 0x14 (Write:0x28, Read:0x29)
I2C-2	M Sensor	2.5 Mbps		AK09911 / M-Sensor I2C Address: 0x0D (Write:0x1A, Read:0x1B)
	Gyro Sensor	400 Kbps	Yes.	ITG1010 / Gyro I2C Address: 0x68 (Write:0xD0, Read:0xD1)
	Accelerometer	400 Kbps		MC3410 / Accelerometer I2C address: 0x4C (Write:0x98, Read:0x99)
	RGB / PS Sensor	400 Kbps		CM36652 / RGB+PS I2C address: 0X60 (Write:0xC0, Read:0xC1)
	NFC	1.2 Mbps	Yes.	MT6605 / NFC I2C address: 0X28 (Write:0x50, Read:0x51)
	Flashlight Driver	400 Kbps		LM3642 / Flashlight Driver I2C address: 0X63 (Write:0xC6, Read:0xC7)
I2C-3				
Note : I2C Spec. : Standard mode (100 kbps) and Fast mode (400 kbps), Fast mode Plus (1 Mbps) and High-speed mode (3.4 Mbps)				

V0.1 First Release (2014/09/05)

V0.2 Change Notice (2014/10/04)

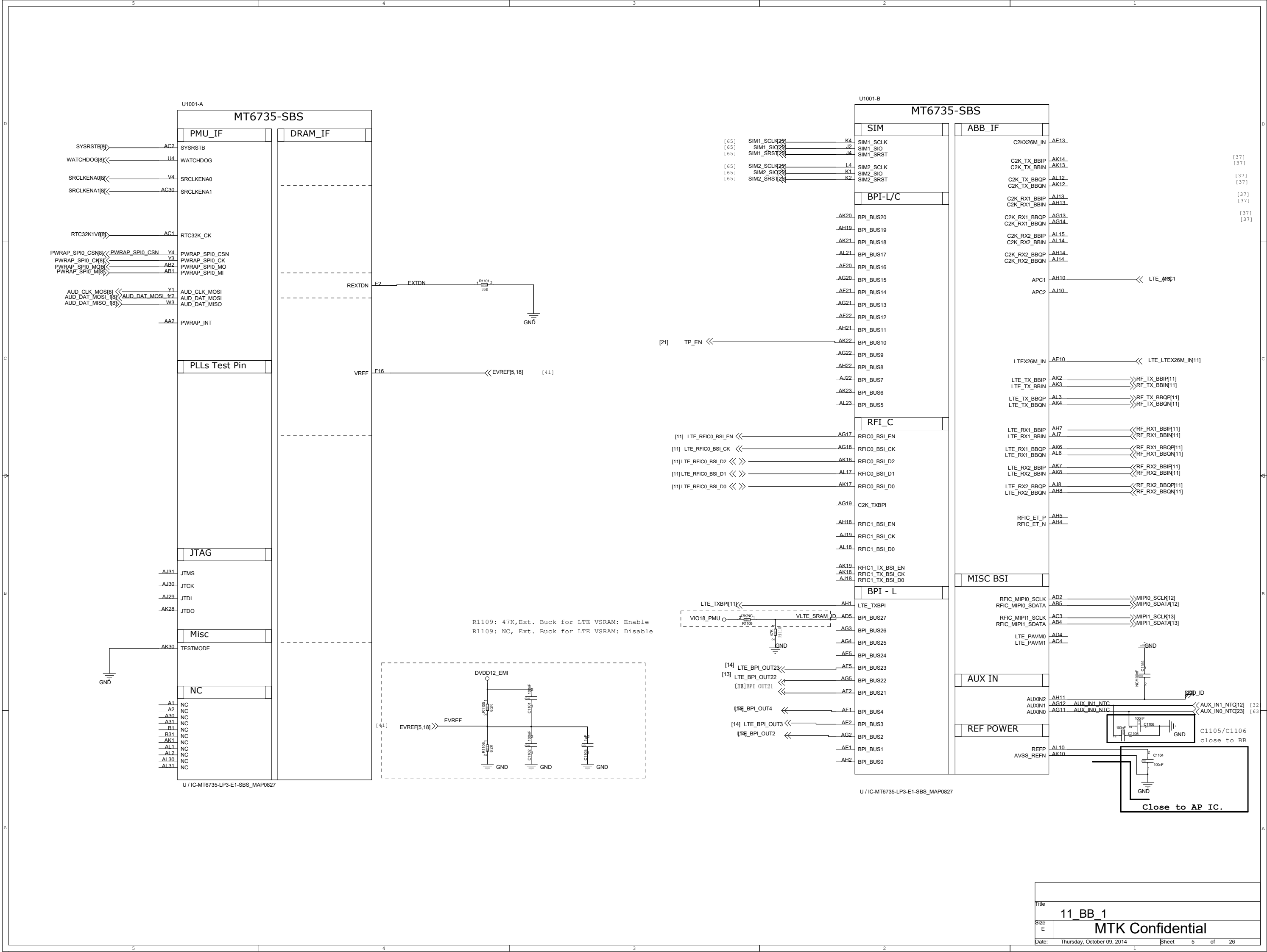
1. Modify Circuit and Cap of VPROC / VLTE / VPCORE / DVDD12\_EMI to sync with MMD Circuit [P10]
2. Modify VIO18 CAP
  - Change C10093 from 1uF to 220nF [P10]
  - Change C10094 from 1uF to 220nF [P10]
  - Change C10100 from 1uF to 100nF [P10]
  - Change C4101 from 2.2uF to 1uF [P41]
  - Change C5121 from 1uF to 100nF [P51]
  - Change C3706 from 2.2uF to 1uF [P37]
3. Add Notice for DVDD18\_MC0/DVDD28\_MC1 Cap [P10]
4. Delete UCTS0/URTS0 net [P12, 90]
5. Delete C2024 and connect AUXADC\_VIN to D\_GND directly [P20]
6. Rename R2004 to R2005 (sync with MMD circuit), and change from 200K to 1R [P20]
7. Delete SH2102 and connect CS\_P to D\_GND [P21]
8. Delete SH2101 [P21]
9. Change C4103 & C4104 from 10uF/C0603 to 2.2uF/C0402 [P41]
10. Delete Notice for Camera [P62]
11. Change U5003 from GPS SAW to GNSS SAW/B8313 [P50]
12. Change R1101 from 240R to 35R [P11]
13. Add Notice for Bypass CAP close to AVDD18\_MEMPLL(E1 ball) & DVDD18\_MC1(F3 ball) [P10]
14. Delete C2058~C2061 [P20]
15. Rename C2037 to C2040 (sync with MMD circuit) and add notice for C2040 [P20]
16. Rename SH2006~SH2010 to sync with MMD circuit [P20]
  - Rename SH2006 to SH2009
  - Rename SH2007 to SH2010
  - Rename SH2008 to SH2011
  - Rename SH2009 to SH2012
  - Rename SH2010 to SH2013 and modify description to NC/MMD/PMIC
17. Add SH2014 [P20]
18. Modify L2001/L2003/L2006/L2008/L2009 value description [P20]
19. Change net name VBAT\_RF to VBAT [P32]
20. Change C3356 from NC to 47pF [P33]
21. Change R3802 from 0R to NC [P38]
22. Change LPF3801 from NC to LPF / FI-168L083523-T [P38]
23. Remove LPF3803/R3811/L3822/L3815 [P38]
24. Remove SH3126/SH3127/SH3128 [P31]
25. Remove SH3125 [P32]
26. SH3129 change to R3215 [P32]
27. SH3123 change to R3216 [P32]
28. SH3124 change to R3217 [P32]
29. Add notice for C3239: Put near PA Sky77621 side [P32]
30. Change SH4101 size from 0603 to 0201 (Sync with MMD) [P41]
31. Connect CON3301 pin3 & pin4 to GND [P33]
32. Modify notice for CON2101 pin1 (Bat connector-VBAT net) from 60mil to 125mil [P21]
33. Add notice for CON2101 pin3 (Bat connector-GND net), need 125mil [P21]
34. Rename bypass cap to sync with MMD circuit [P10]
  - Rename bypass cap for AVDD28\_DAC from C10080 to C10090
  - Rename bypass cap for DVDD18\_IOLT from C10086 to C10096
  - Rename bypass cap for DVDD18\_IOLB from C10087 to C10097
35. Rename bypass cap for AVDD18\_AUD from C2040 to C2058 [P20]
36. Modify notice for AVDD45\_VSYS22 balls, change form 20mil to 30mil [P20]
37. Modify notice for AVDD45\_VPA ball, change form 20mil to 30mil [P20]
38. Add trace width notice for Buck [P20]

V0.3 Change Notice (2014/10/24)

1. Delete CORESONIC\_SWDC/CORESONIC\_SWCK net [P12, 90]
2. Modify R1105 & R1106 from 8K to 8.06K [P11]
3. Update U2402 complete part number: FAN53611AUC115X [P24]
4. Modify C10082 from 100nF to NC [P10]
5. Add Note12-1 & 12-2 for MT6735M [P12]
6. Connect GND\_VLTE from SH2003 to SH2002 [P20]
7. Connect GND\_VCORE1 from SH2002 to SH2003 [P20]
8. Change SH3903 to R3909 /0402/NC [P39]
9. Change SH3904 to R3910/0402/OR [P39]
10. Change PA3901 from RF7255 to SKY77765 [P39]
11. Change R3702 from OR to 68R [P37]
12. Change R3701/3703 from NC to 100R [P37]
13. Modify R1101 from 35R to 36R [P11]
14. Modify R6510 Circuit [P65]
15. RF Phase2 first release [P31-34]

Title			
05_Change Notice			
Size E	MTK Confidential		
Date:	Thursday, October 09, 2014	Sheet	3 of 26





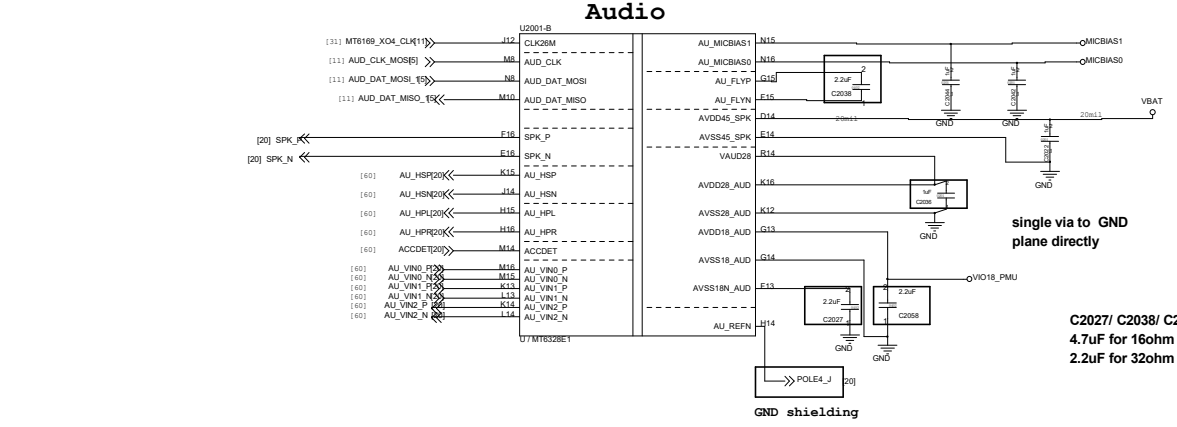
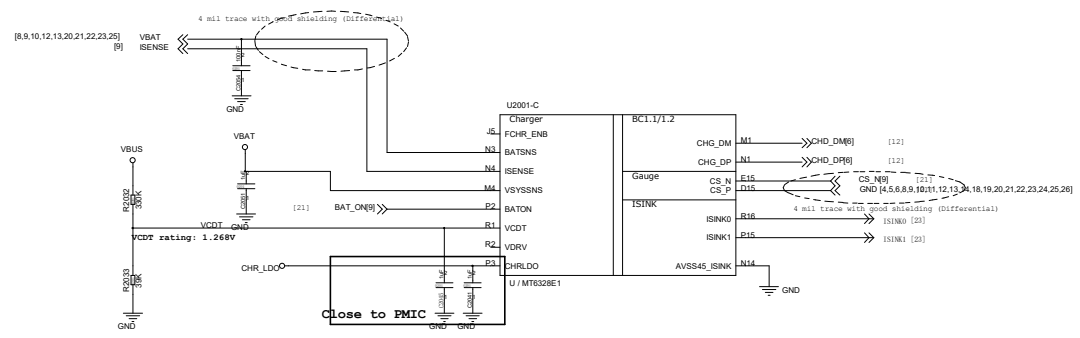




1. VBAT Buck input cap should connect to its individual GND first, then go to main GND.
2. Buck controller power trace (AVDD45\_80P5) must use single trace connected to system (battery) power directly, and can't merge with others.
3. Please refer to latest MMD design

Regulator	Output Voltage Range(V)	Output Current(mA)	Input Decoupling Cap	Output Decoupling	Note
VPROC	0.6~1.31	5000	>2.2uF	0.33uH+47uF*2+22uF	≥125mil
VCORE	0.6~1.31	3500	>2.2uF	0.47uH+47uF*2	≥88mil
VLTE	0.6~1.31	2800	>2.2uF	0.47uH+22uF*3	≥63mil
VSYS	2	1900	>2.2uF	0.47uH+22uF+10uF	≥48mil
VPA	0.5~3.4	600	>4.7uF	2.2uH+2.2uF+2.2uF	≥30mil
VM	1.24/1.39/1.54	1000		9.4uF~10uF	L/W=1500mil/25mil
VTXO_0	2.8	40		1uF~3uF	L/W=2800mil/6mil
VTXO_1	2.8	40		1uF~3uF	L/W=2800mil/6mil
VRFB_0	1.825	350		2.2~3.3uF	L/W=2800mil/10mil
VRFB_1	1.2/1.3/1.5/1.825	300		2.2~3.3uF	L/W=2800mil/10mil
VSIM1	1.7/1.8/1.86/2.76/3.0/3.1	50		1uF~3uF	L/W=2800mil/6mil
VSIM2	1.7/1.8/1.86/2.76/3.0/3.1	50		1uF~3uF	L/W=2800mil/6mil
VON18	1.8	150		1uF~3uF	L/W=2800mil/10mil
VON28	2.8	40		1uF~3uF	L/W=2800mil/6mil
VON33	3.0/3.1/3.2/3.3/3.4/3.5/3.6	350		4.7uF~5uF	L/W=2800mil/12mil
VO18	1.8	600		2.2~6.6uF	L/W=2800mil/20mil
VUSB33	3.3	20		1uF~3uF	L/W=2800mil/6mil
VO28	2.8	200		2.2~6.6uF	L/W=2800mil/10mil
VEFUSE	1.8/1.9/2.0/2.1/2.2	200		1uF~3uF	L/W=2800mil/10mil
VMC	1.8/2.9/3.0/3.3	200		1uF~3uF	L/W=2800mil/10mil
VMCH	2.9/3.0/3.3	800		4.7uF~7uF	L/W=2800mil/20mil
VEMC_3V3	2.9/3.0/3.3	400		4.7uF~7uF	L/W=2800mil/12mil
VCAMA	1.5/1.8/2.5/2.8	200		2~3.3uF	L/W=2800mil/10mil
VCAMAF	1.2/1.3/1.5/1.8/2.0/2.8/3.0/3.3	200		2~3.3uF	L/W=2800mil/10mil
VCAMD	0.9/1.0/1.1/1.22/1.3/1.5	500		4.4uF~6.9uF	L/W=2800mil/16mil
VCAMIG	1.2/1.3/1.5/1.8	200		1uF~3uF	L/W=2800mil/10mil
VGP1	1.2/1.3/1.5/1.8/2.5/2.8/3.0/3.3	200		1uF~3uF	L/W=2800mil/10mil
VSRAM	0.6~1.31	400		4.7uF~7uF	L/W=2800mil/12mil
VIBR	1.2/1.3/1.5/1.8/2.0/2.8/3.0/3.3	100		1uF~3uF	L/W=2800mil/8mil
VAUX18	1.8	40		1uF~3uF	L/W=2800mil/6mil
VAUD28	2.8	40		1uF~3uF	L/W=2800mil/6mil
DVDD18_DIG	1.8	20		1uF	L/W=800mil/4mil
VRTC	2.8	2		0.1uF	L/W=800mil/4mil

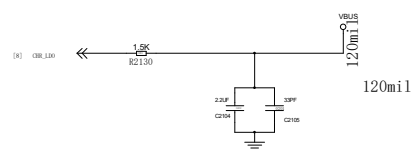
VIBR



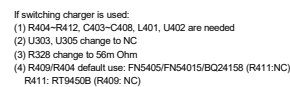
To improve noise level, connect to audio jack first, and then connect to GND

C2027/ C2038/ C2058 flying cap & holding cap :  
4.7uF for 16ohm receiver  
2.2uF for 32ohm receiver

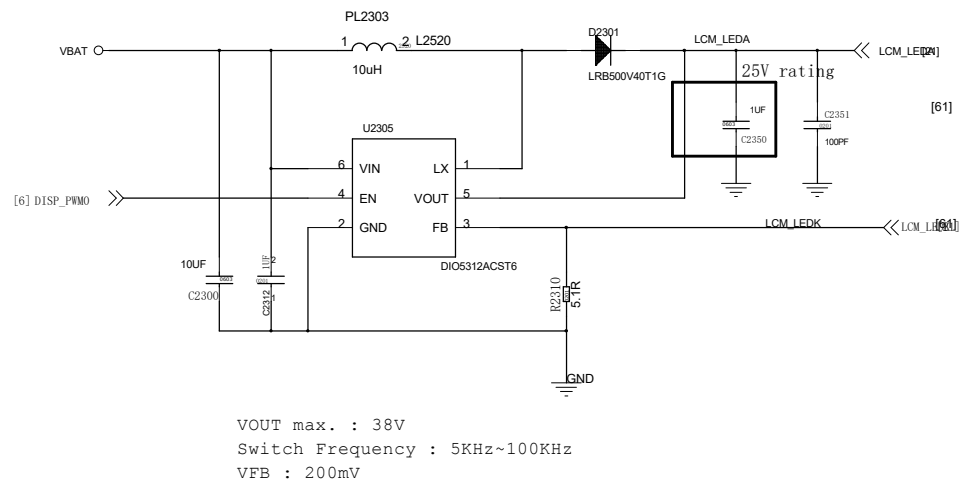




## Rest



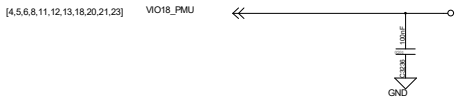
LCM Backlight LED Driver



Flash LED 5V Boost

Flash LED I2C address: 0X63 (Write:0xC6, Read:0xC7)



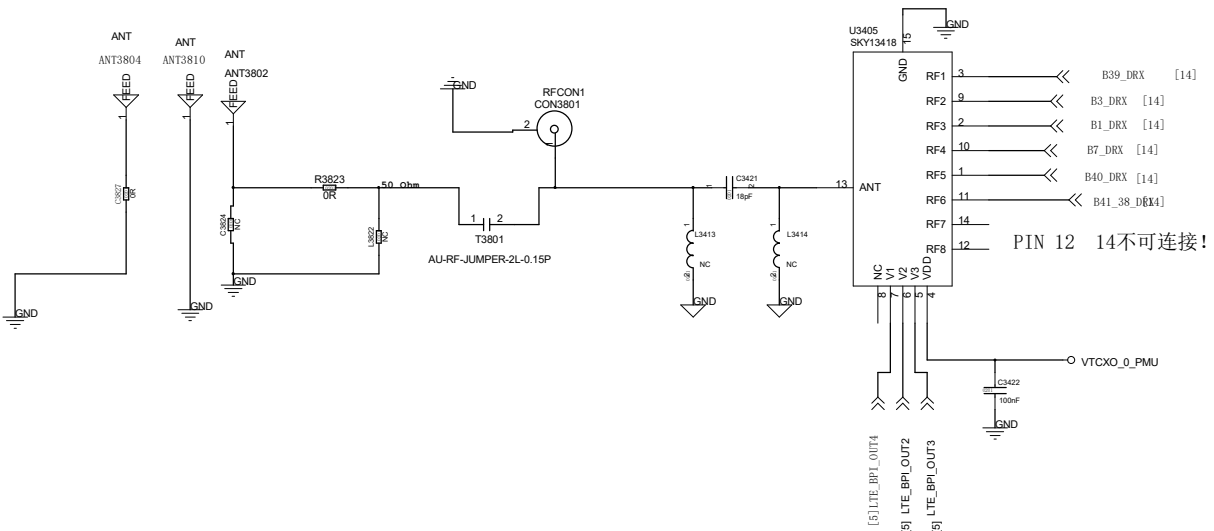


V0.02\_2  
R3224 keep 10mm far from 77621 and 7778  
10mil

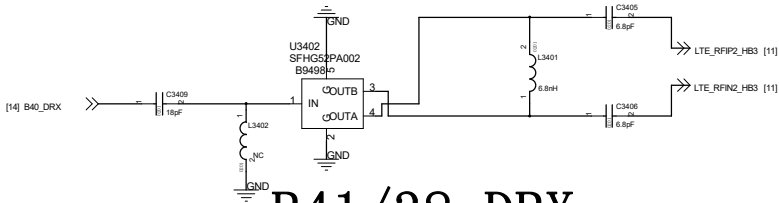
VBAT : 80mil



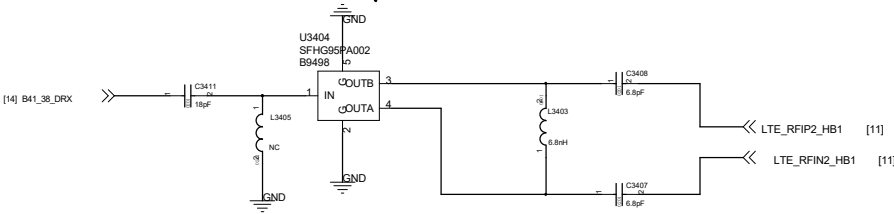
DRX ANT: 704~2690MHz



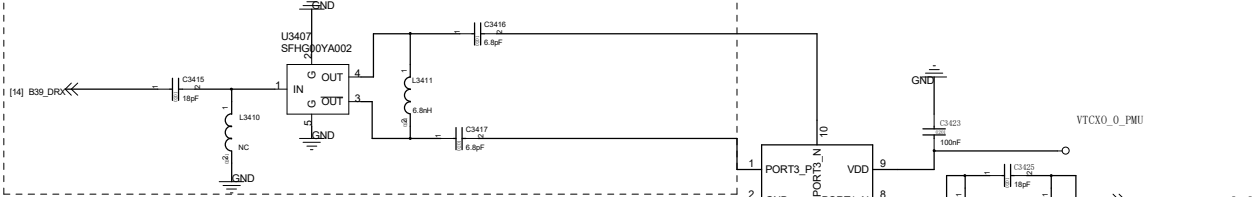
B40 DRX



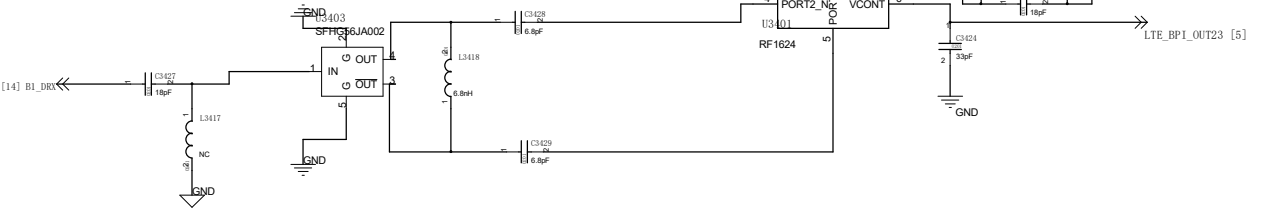
B41/38 DRX



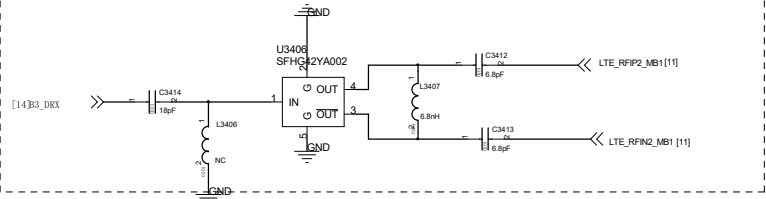
B39 DRX



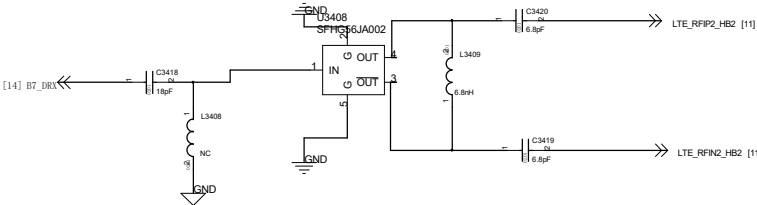
B1 DRX



B3 DRX



B7 DRX





CA[0..9]	CA[0..9]
----------	----------

MSDC0_RSTB	MSDC0_RSTB
MSDC0_CMD	MSDC0_CMD
MSDC0_CLK	MSDC0_CLK
MSDC0_DSL	MSDC0_DSL
MSDC0_DAT0	MSDC0_DAT0
MSDC0_DAT1	MSDC0_DAT1
MSDC0_DAT2	MSDC0_DAT2
MSDC0_DAT3	MSDC0_DAT3
MSDC0_DAT4	MSDC0_DAT4
MSDC0_DAT5	MSDC0_DAT5
MSDC0_DAT6	MSDC0_DAT6
MSDC0_DAT7	MSDC0_DAT7

Power I/F

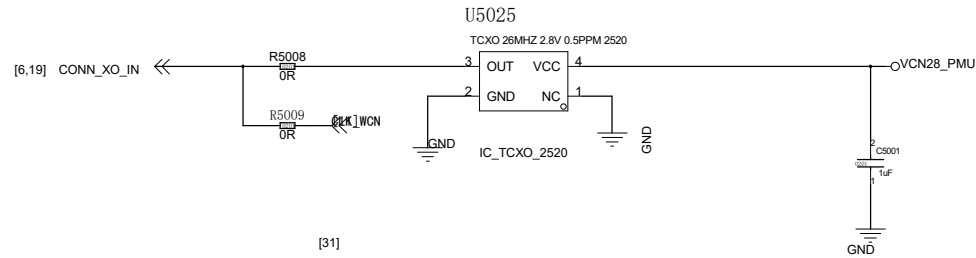
**221 Ball, 0.5mm pitch**

**VDD1=1.8V**

Hynix/H9TQ64A8GTMCUR-KUM



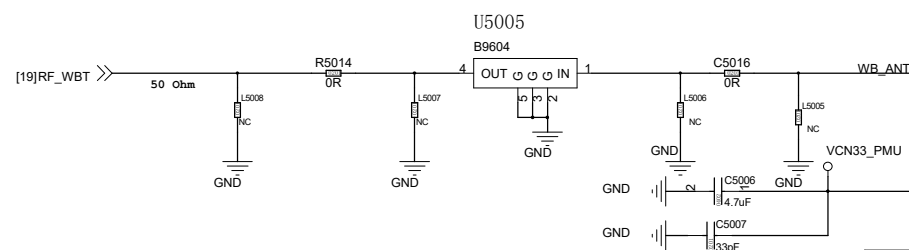
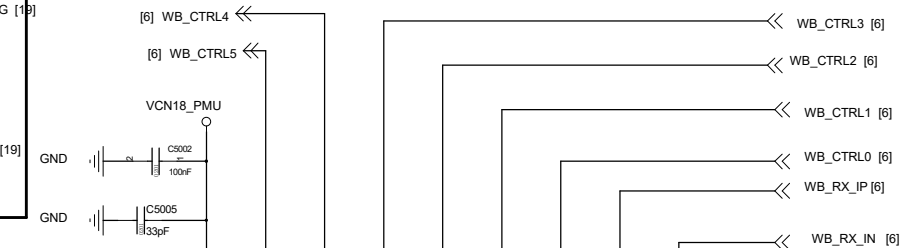
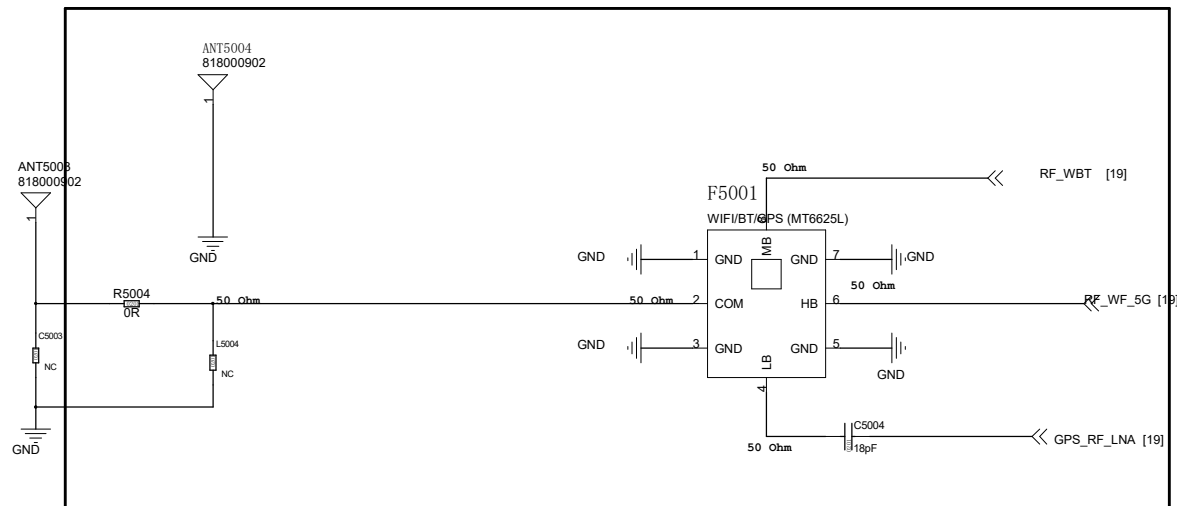




Close to Antenna

Same layer as Antenna, 50ohm trace reference to 3rd layer GND(2nd Layer clean)

Reserve Keep out region from L1 to Main GND layer

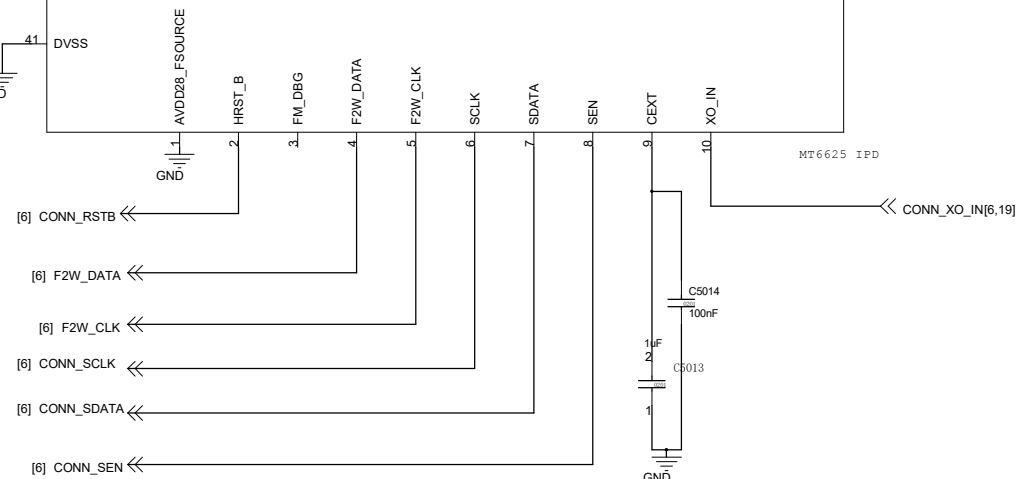
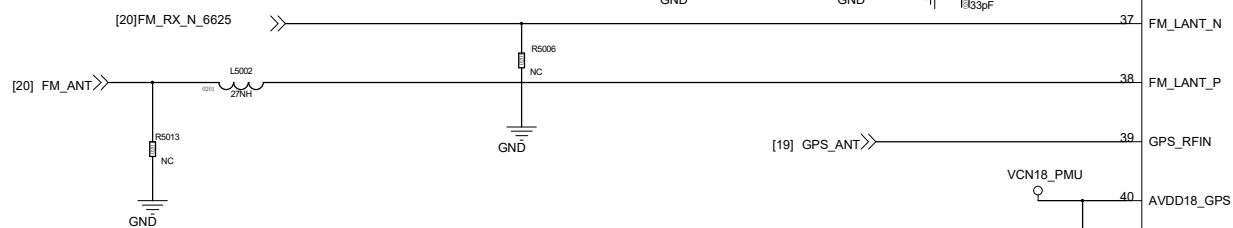


<Critical!!>

5G PCB loss is higher and  
Trace must kept short and 50-Ohm  
No layer transition

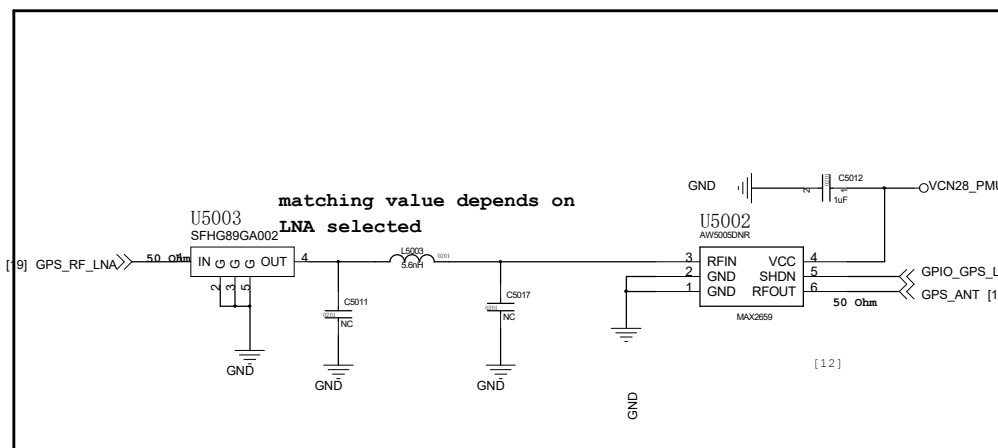
Close to MT6625

U / MT6625L / QFN40



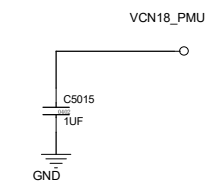
Close to ANT

GPS xLNA



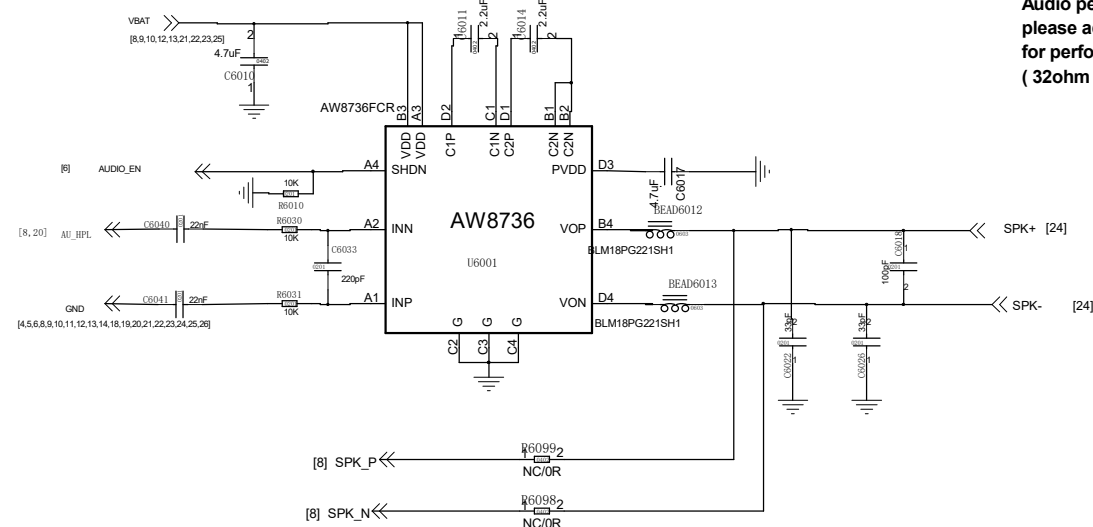
matching value depends on  
LNA selected

Same layer as Antenna, 50ohm trace reference to 3rd layer GND(2nd Layer clean)

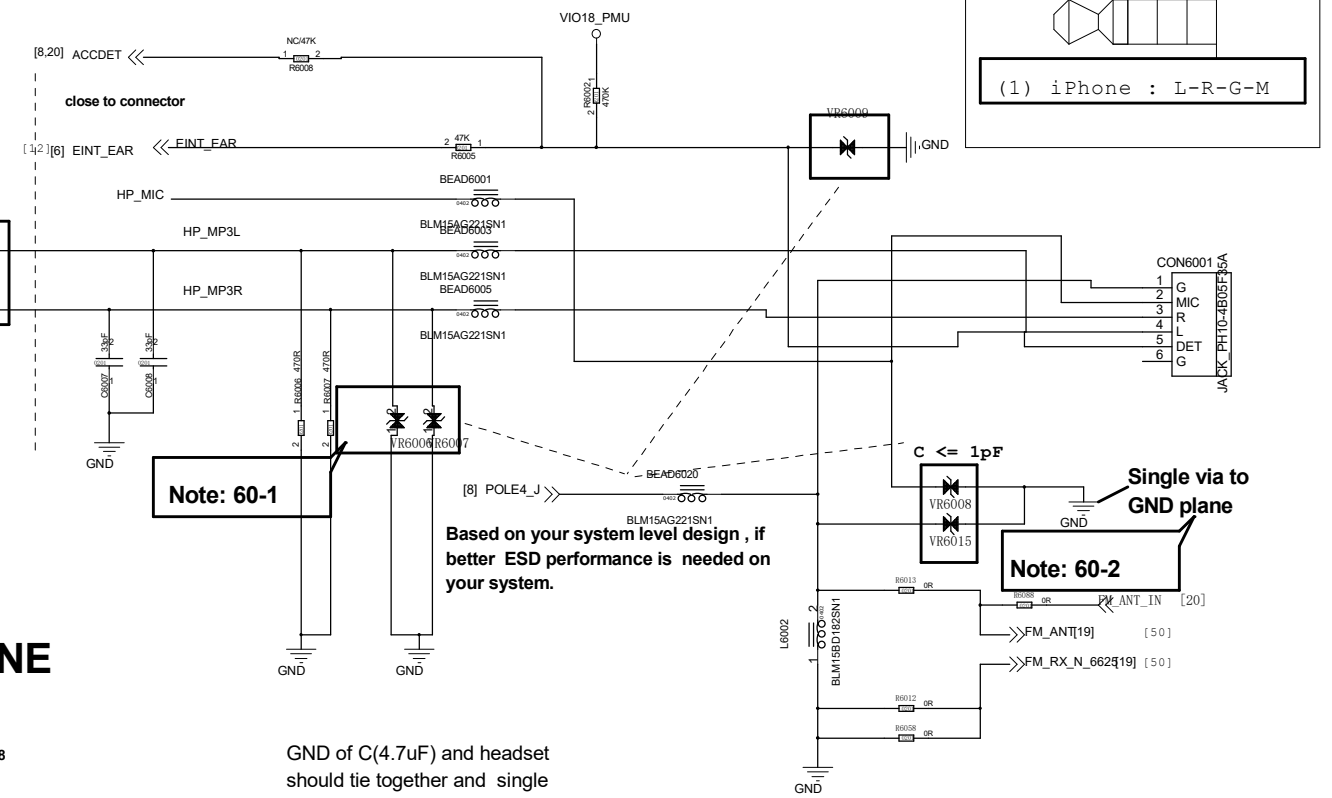


## Earphone Audio

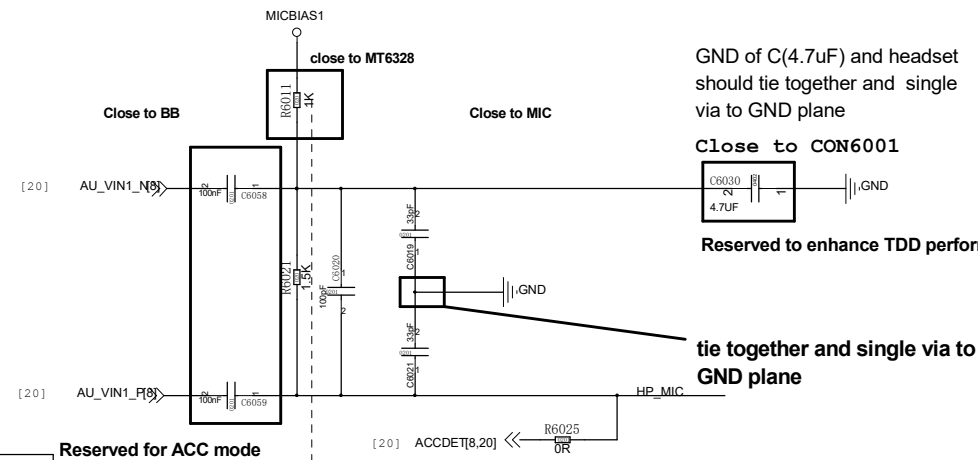
**Based on your system level design , if better Audio performance is needed on your system, please add 32ohm to audio path for performance enhance proposal ( 32ohm condition pop noise can improve 6dB )**



**BEAD6002 / BEAD6004 are  
for FM-desense tuning proposal**



## Earphone MICPHONE



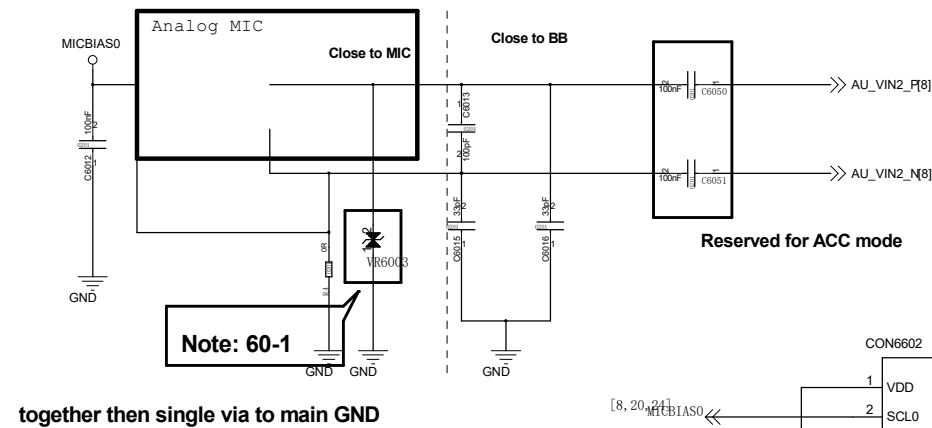
GND of C(4.7uF) and headset should tie together and single via to GND plane

Close to CON6001

Reserved to enhance TDD performance

tie together and single via to GND plane

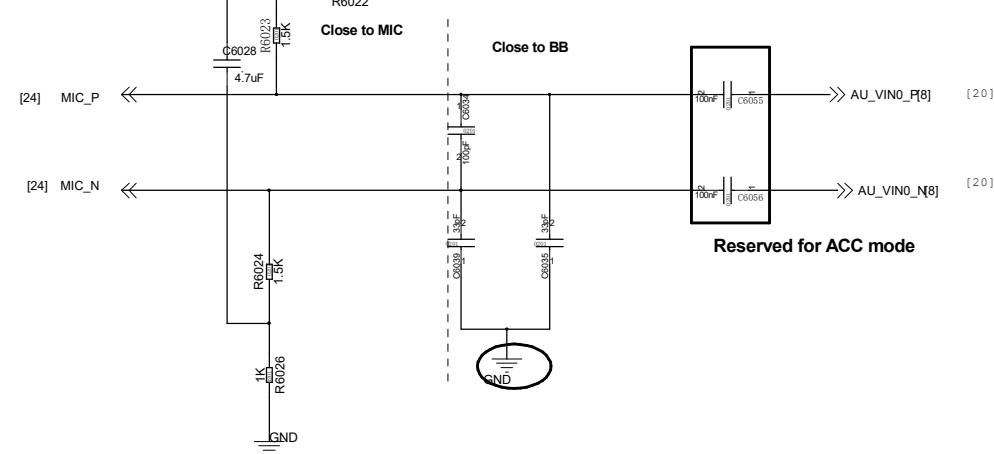
## Handset Microphone 2



**Note: 60-1**

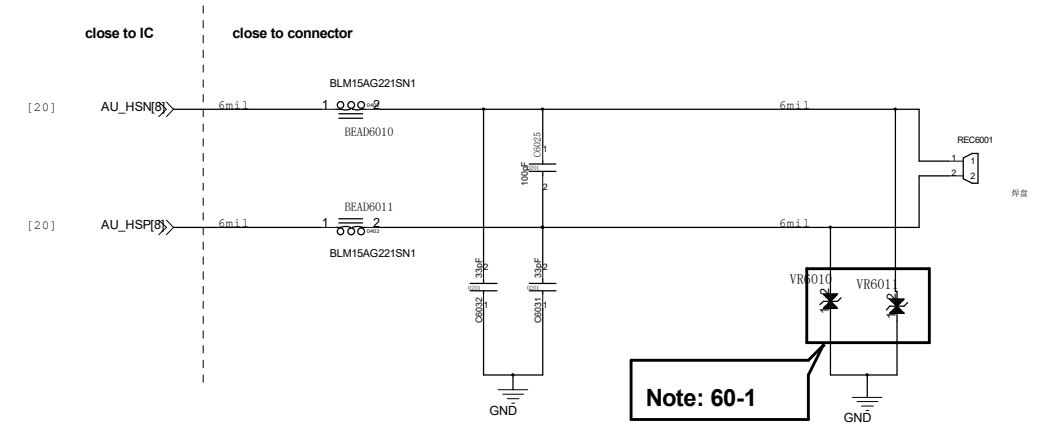
**together then single via to main GND**

## Main Microphone 1



Reserved for ACC mode

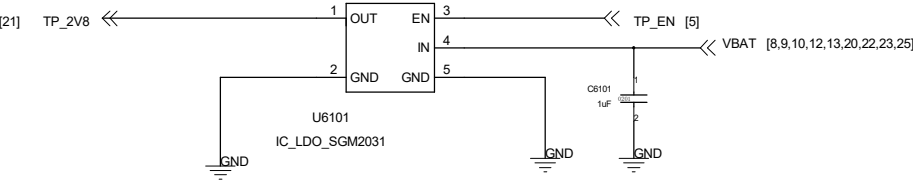
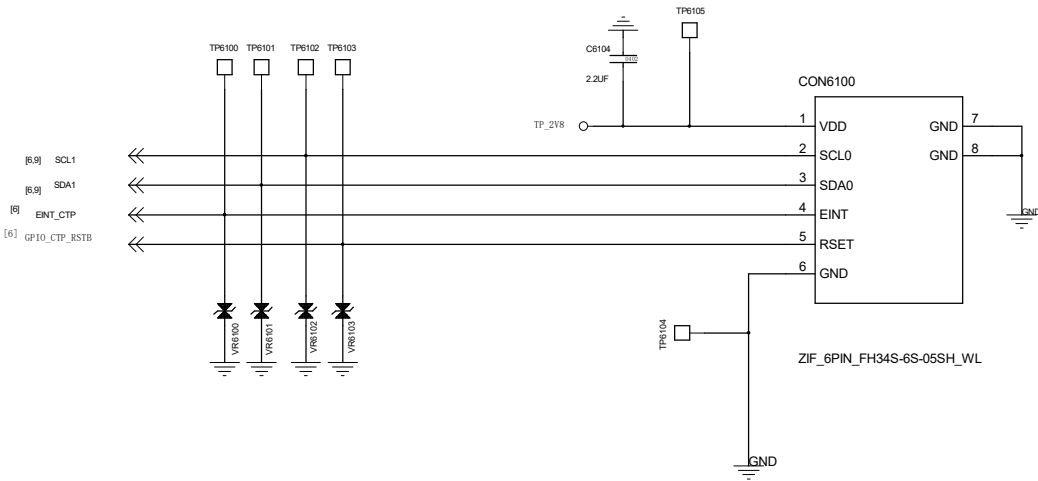
## Receiver



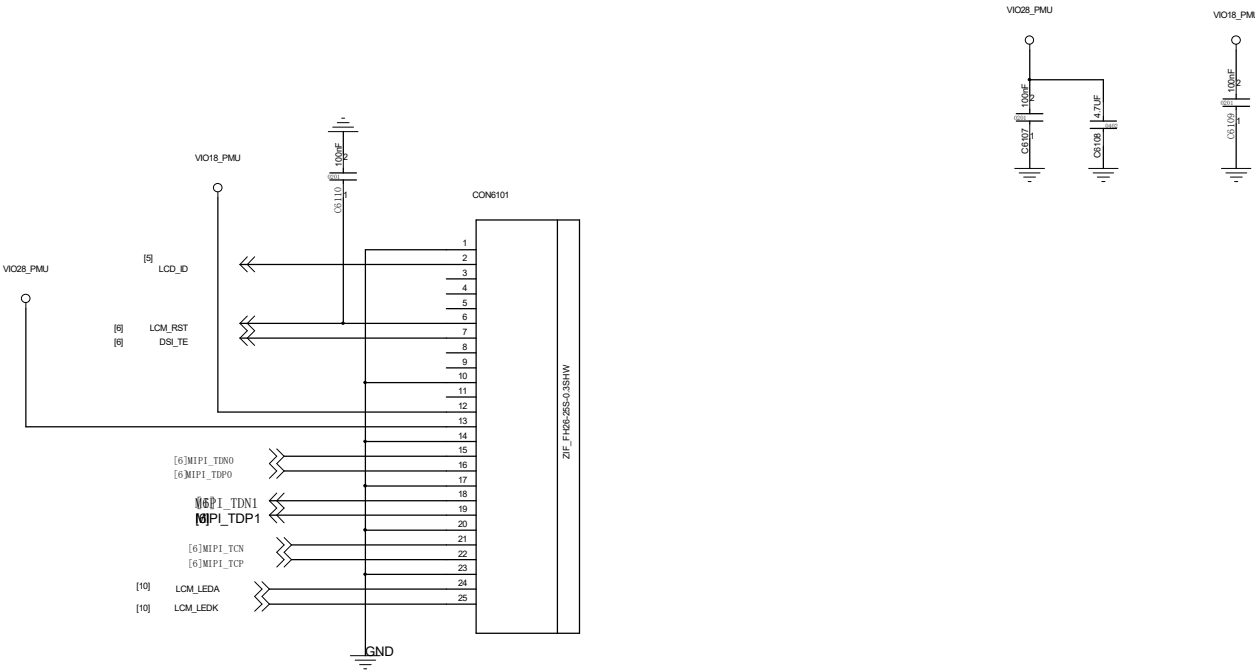
**Note: 60-1**

Based on your system level design , if better ESD performance is needed on your system.

CTP Connector



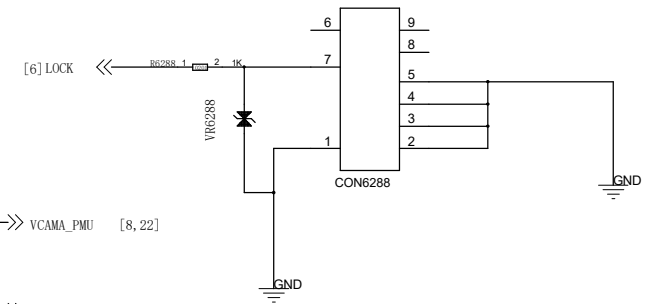
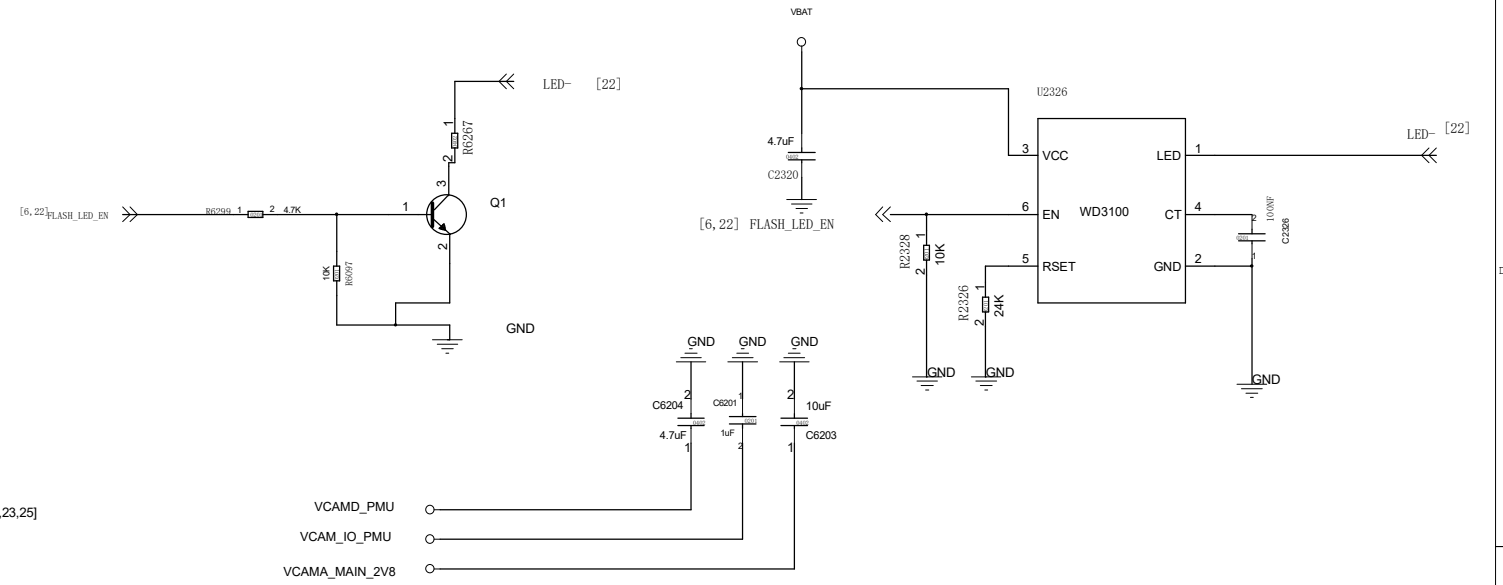
Main LCM



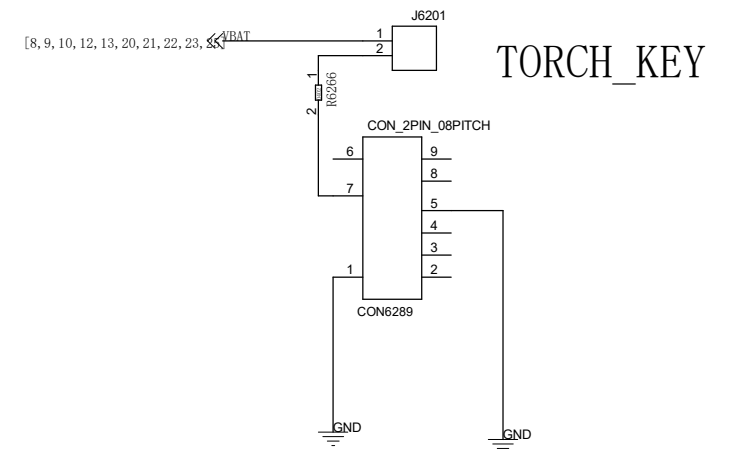
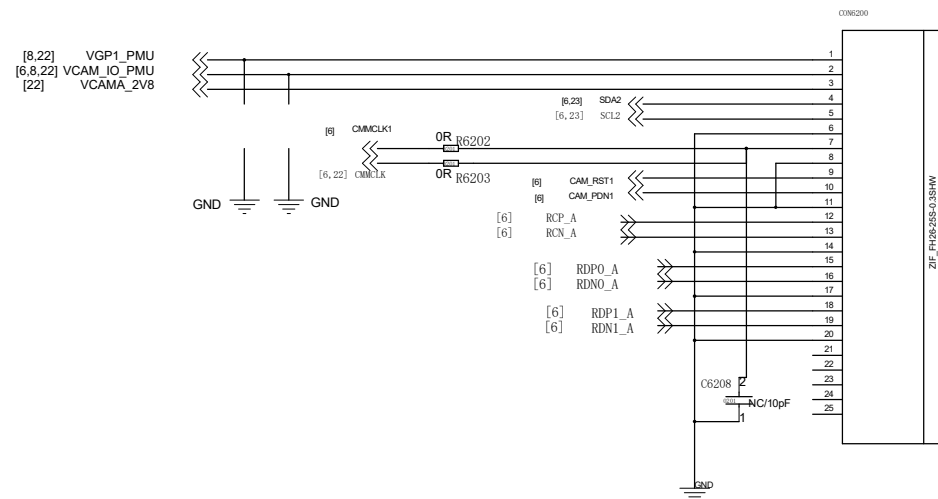
Schematic design notice of "61\_PERI\_LCD\_CTP" page.

Note 61-1: GT1151 I2C address: 0X5D (Write:0xBA, Read:0xBB) or 0x14 (Write:0x28, Read:0x29)

```
Rear camera (IMX135) I2C address: 0X10 (Write:0x20, Read:0x21)
AF driver (DW9714A) I2C address: 0x0C (Write:0x18 , Read:0x19)
```

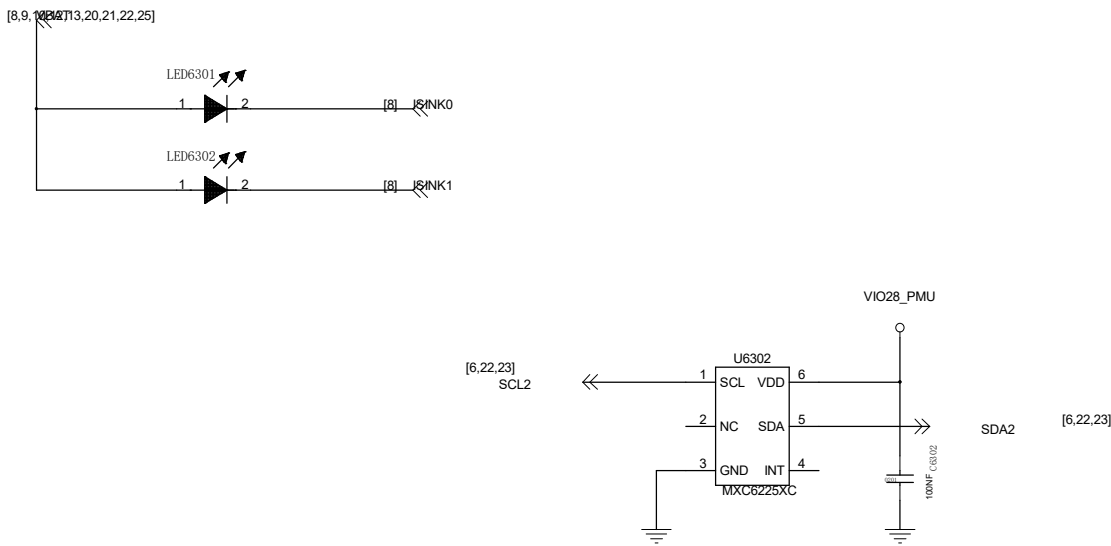


Front camera (GC2355) I2C address: 0x3C (Write:0x78, Read:0x79)



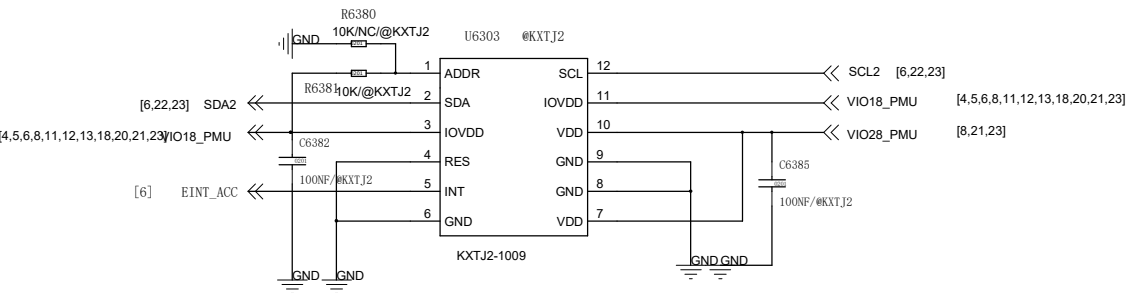
M-Sensor

M-Sensor I2C Address: 0x0D (Write:0x1A, Read:0x1B)

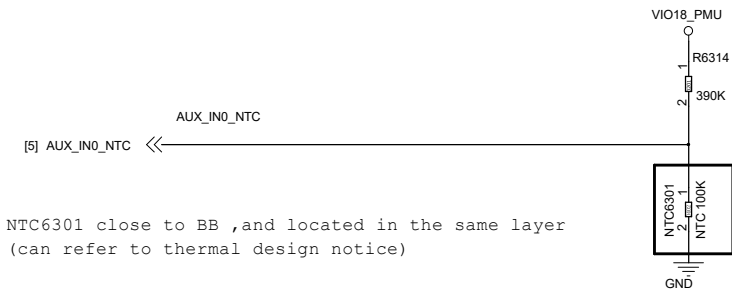


Accelerometer

MC3410 / Accelerometer I2C address: 0x4C (Write:0x98, Read:0x99)



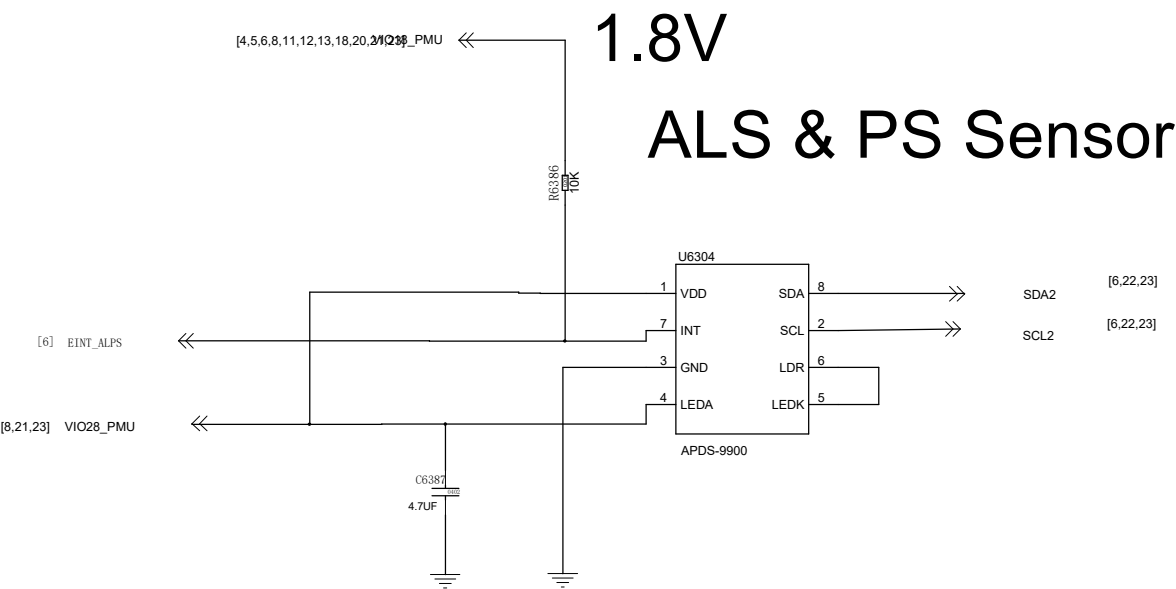
Thermistor / To sense board level temperature



NTC6301 close to BB ,and located in the same layer (can refer to thermal design notice)

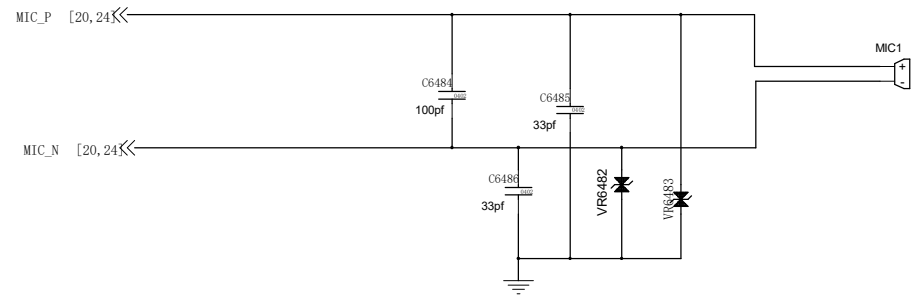
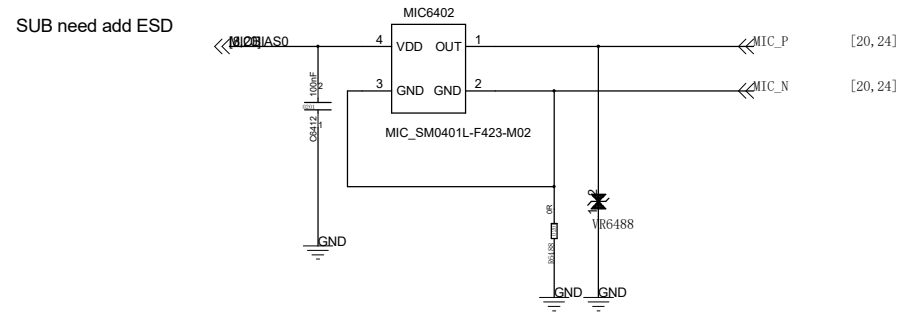
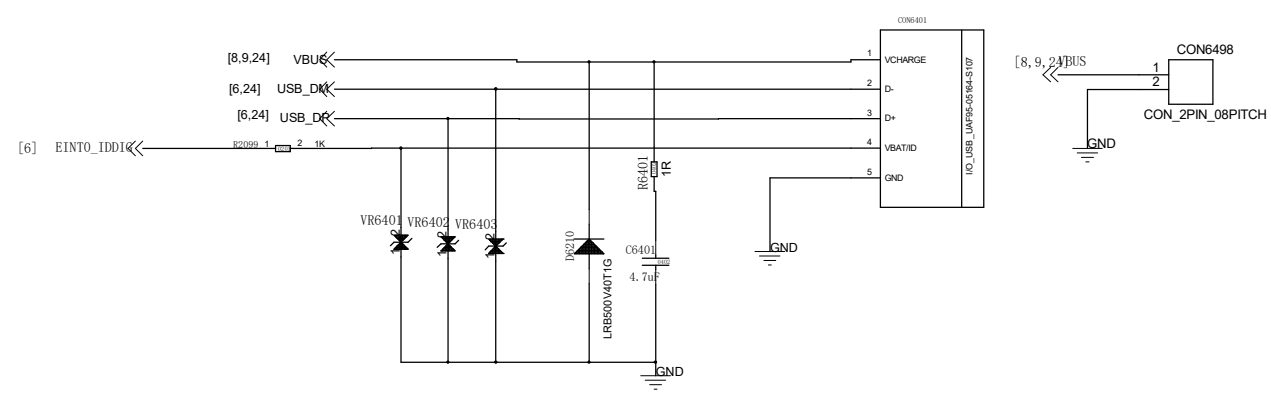
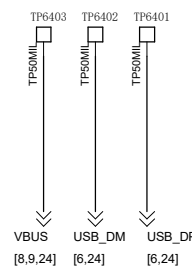
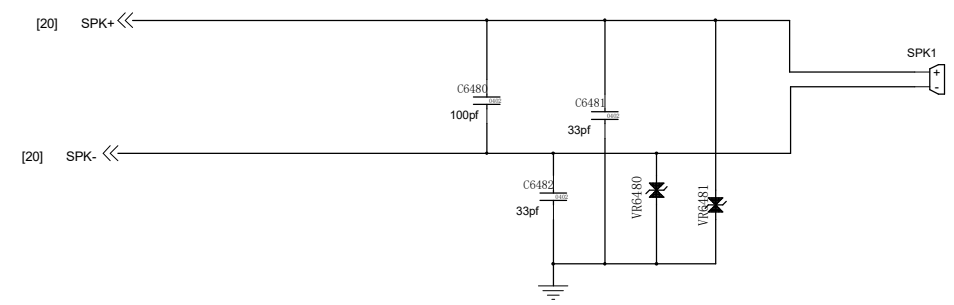
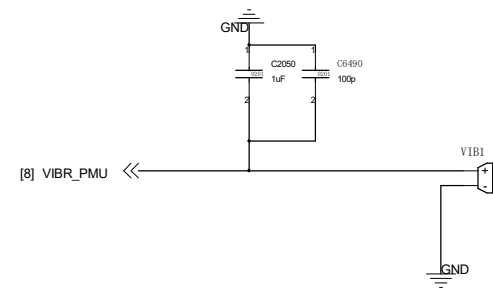
ALS & PS Sensor

CM36652 / RGB + PS I2C address: 0X60 (Write:0xC0, Read:0xC1)



	PCB	Note
AUX_IN0_NTC	AP	Keep 5-8 mm to AP, and far to other heat source

Sub Connector

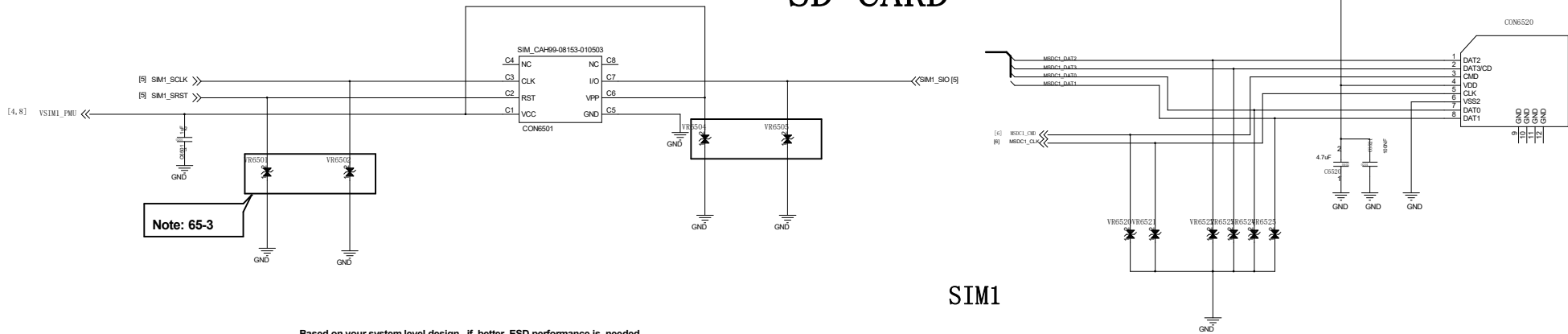


Schematic design notice of "64\_PERI\_USB\_MHL" page.

The equivalent capacitance of USB2.0 ESD protection device must be <=3pF.  
For D+/D- 2-ch TVS device is also available for smaller layout area

SIM1

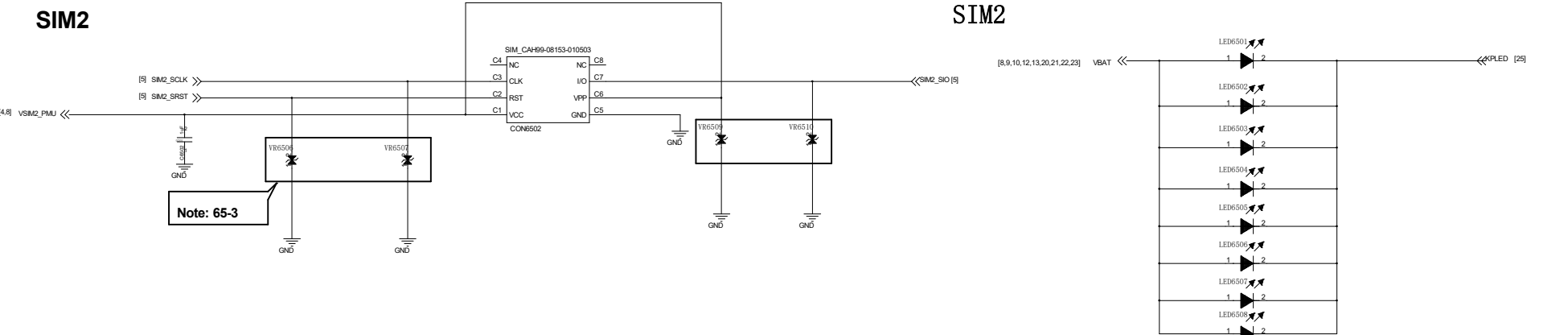
SD CARD



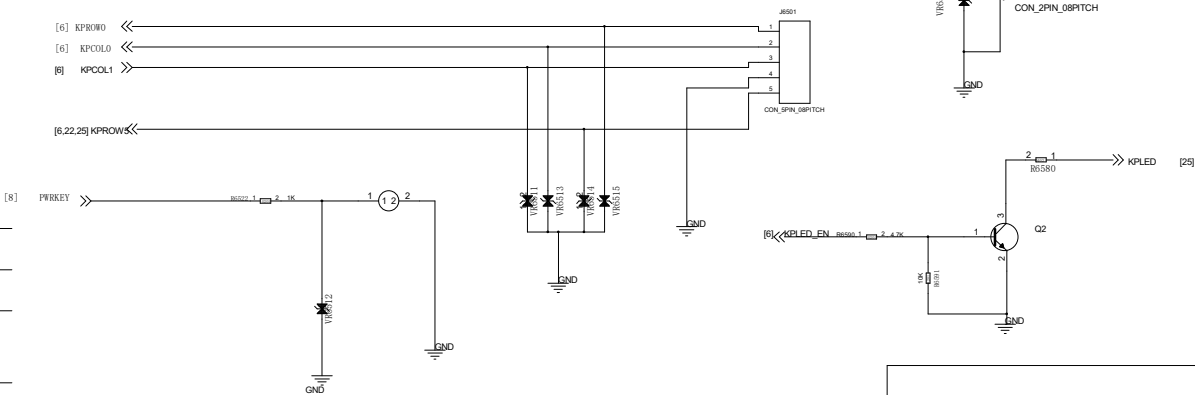
SIM1

SIM2

SIM2



PWRKEY



Schematic design notice of "65\_PERI\_Dual\_SIM\_ICUSB\_KEYPAD" page.

Note 65-1: DO NOT put pull-up resistor on PWRKEY

Note 65-2: Volume Up : HOME Key / GND  
Volume Down : KPROW0/KPCOL0

Note 65-3: The equivalent capacitance of SIM ESD protection device must be <=22pF.  
But for NFC app. equivalent capacitance of NFC\_SWP should <=0.5pF.

65 PERI Dual SIM KEYPAD  
MTK Confidential

Thursday, October 06, 2014 10:25 AM

